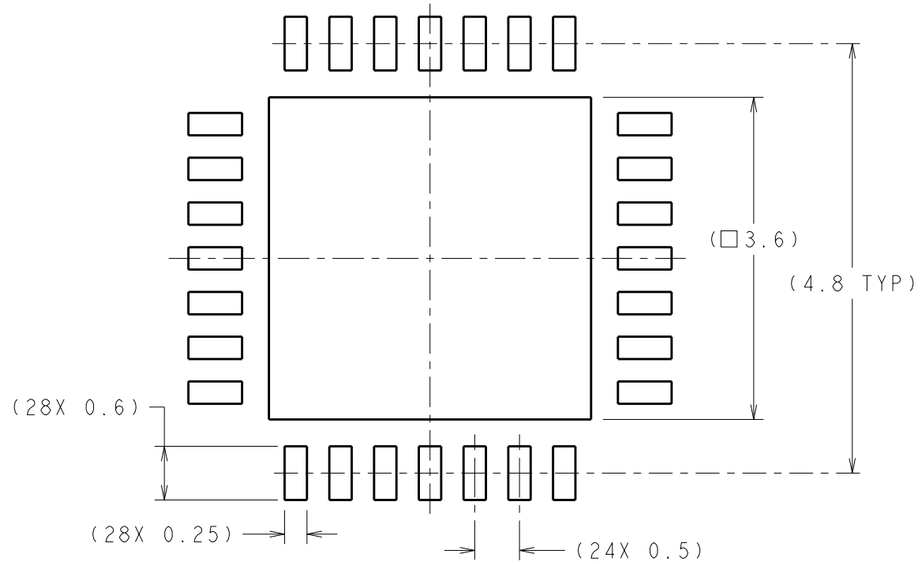
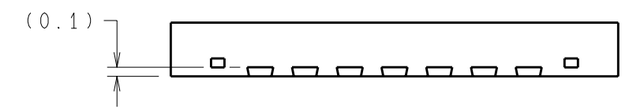
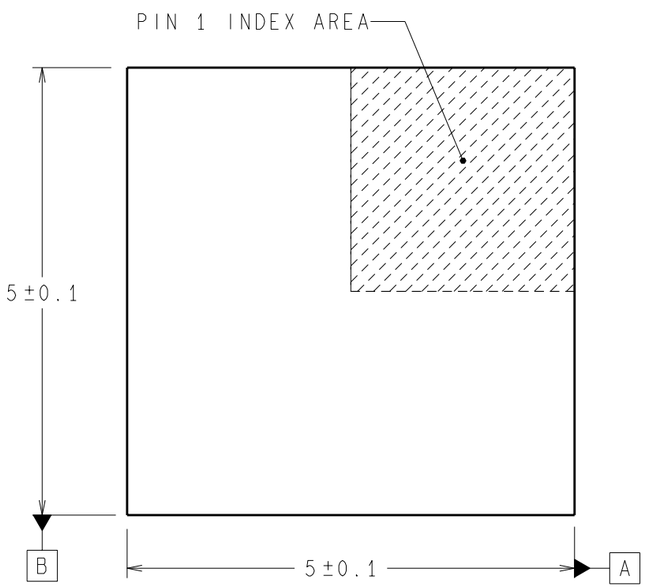
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1163	08/15/2003	AS/TL/SN

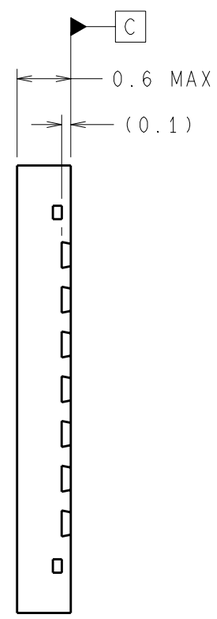


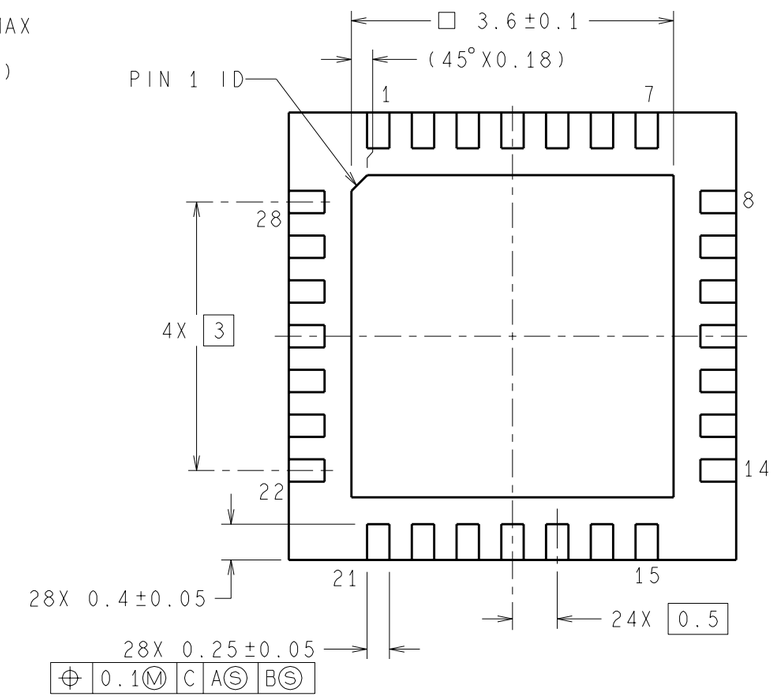
RECOMMENDED LAND PATTERN

DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN ( ) FOR REFERENCE ONLY









NOTES: UNLESS OTHERWISE SPECIFIED.

1. FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. MAXIMUM ALLOWABLE METAL BURR ON LEAD TIPS AT THE PACKAGE EDGES IS 76 MICRONS.
3. REFERENCE JEDEC REGISTRATION MO-220, VARIATION WHHD-3.

APPROVALS	DATE
DRAWN ASNOR SULAIMAN	08/15/2003
DFTG. CHK. THANH LEQUANG	08/15/2003
ENGR. CHK. N. SANTHIRAN	08/15/2003

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LLP, PLASTIC, QUAD, 5x5x0.6mm BODY, 28 LD 0.5mm PITCH, NO PULLBACK

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-SPA28A	A

FORMERLY: N/A

SHEET 1 of 1